

## QML MEMORY PRODUCTS / CUSTOM PACKAGING



### CUSTOM PACKAGING

DPACI's Total Solutions approach means that we have the complete capability to manufacture, test and deliver high reliability components under one roof. We can package and assemble semiconductors and microcircuits to Class "B" and Class "S" requirements of MIL-PRF-38535. We also assemble and test hybrids to specific customer requirements.



All assembly operations take place in our self-contained, stand-alone Class 10,000 clean room (ISO Class 7). Highly skilled personnel perform all assembly processes under Class 100 (ISO Class 5) laminar flow hoods, using state-of-the-art assembly equipment.

Manufacturing processes required to package monolithic microcircuits, semiconductors and hybrids are performed to documented procedures, inspected to exacting specifications by experienced quality control personnel and include First Article Testing within the clean room environment.

The manufacturing processes that we perform in our clean room include:

- ◆ Wafer Processing
- ◆ Die Attaching
- ◆ Wire Bonding
- ◆ First Article Validation
- ◆ In-Line Inspection
- ◆ Quality / Reliability Testing
- ◆ Package Sealing



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